

APPARATUS FOR STACKING SEMICONDUCTOR CHIPS

Abstract of Disclosure

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A multi-chip memory module comprises multiple standard, surface-mount-type memory chips stacked on top of each other, and a pair of printed circuit boards mounted on opposite sides of the memory chips to electrically interconnect the memory chips. Each printed circuit board has vias that are positioned to form multiple rows, with each row of vias used to connect the printed circuit board to a respective memory chip. The vias falling along the bottom-most row of each printed circuit board are also exposed and are used to surface mount the multi-chip module to pads of a memory board.

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